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INTERNATIONAL STANDARD

NORME INTERNATIONALE

Surface mounting technology – Part 3: Standard method for the specification of components for through hole reflow (THR) soldering

Technique du montage en surface – Partie 3: Méthode normalisée relative à la spécification des composants pour le brasage par refusion à trous traversants (THR, Through Hole Reflow)

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FOREWORD

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The text of this standard is based on the following documents:

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91/856/CDV	91/898/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

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